EESTI STANDARD

EVS-EN IEC 62812:2019

Low resistance measurements - Methods and guidance



EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

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|---|--|--|--|--|
| See Eesti standard EVS-EN IEC 62812:2019 sisaldab Euroopa standardi EN IEC 62812:2019 ingliskeelset teksti. | This Estonian standard EVS-EN IEC 62812:2019 consists of the English text of the European standard EN IEC 62812:2019. | | | |
| Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas | This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation. | | | |
| Euroopa standardimisorganisatsioonid on teinud Euroopa standardi rahvuslikele liikmetele kättesaadavaks 05.07.2019. | Date of Availability of the European standard is 05.07.2019. | | | |
| Standard on kättesaadav Eesti Standardikeskusest. | The standard is available from the Estonian Centre for Standardisation. | | | |
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ICS 31.040.01

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EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM

EN IEC 62812

July 2019

ICS 31.040.01

English Version

Low resistance measurements - Methods and guidance (IEC 62812:2019)

Mesures de faibles résistances - Méthodes et recommandations (IEC 62812:2019) Messung niederohmiger Widerstände - Verfahren und Leitfaden (IEC 62812:2019)

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European foreword

The text of document 40/2665/FDIS, future edition 1 of IEC 62812, prepared by IEC/TC 40 "Capacitors and resistors for electronic equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62812:2019.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2020-03-06 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2022-06-06 document have to be withdrawn

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

| IEC 60115-2 | NOTE | Harmonized as EN 60115-2 |
|---------------|------|----------------------------|
| IEC 60115-8 | NOTE | Harmonized as EN 60115-8 |
| IEC 60301 | NOTE | Harmonized as EN 60301 |
| IEC 61249-5-1 | NOTE | Harmonized as EN 61249-5-1 |
| | | |

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

| Publication | <u>Year</u> | Title | <u>EN/HD</u> | Year |
|-------------------|-------------|--|--------------|------|
| IEC 60068-1 | - | Environmental testing - Part 1: General and guidance | EN 60068-1 | - |
| IEC 60115-1 (mod) | 2008 | Fixed resistors for use in electronic equipment - Part 1: Generic specification | EN 60115-1 | 2011 |
| - | - | | + A11 | 2015 |
| IEC 60294 | - | Measurement of the dimensions of a cylindrical component with axial terminations | EN 60294 | - |
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| | | | | |

CONTENTS

| FOREWO | PRD | 4 |
|------------------------|--|-----|
| 1 Scop | e | 6 |
| 2 Norm | native references | 6 |
| 3 Term | is and definitions | 6 |
| 4 Resi | stance measurement phenomena | 7 |
| 4.1 | General | 7 |
| 4.2 | Lead and contact resistance | 7 |
| 4.3 | Self-heating | 9 |
| 4.4 | Variation of resistance with temperature | 10 |
| 4.5 | Thermoelectric e.m.f. | 12 |
| 4.6 | Peltier effect | 15 |
| 5 Meth | ods of measurement | 16 |
| 5.1 | General | 16 |
| 5.2 | Four-wire resistance measurement | 16 |
| 5.3 | Offset compensation method | 19 |
| 5.4 | Current inversion method | 22 |
| 5.5 | Differential current inversion method | 25 |
| 5.6 | Short-term trigger method | 28 |
| 6 Conr | necting the specimen | 32 |
| 6.1 | Resistors with lead wires for soldered assembly | 32 |
| 6.1.1 | Connecting leaded resistors in a test fixture | 32 |
| 6.2 | Resistors with solder terminations for surface mount assembly | 33 |
| 6.2.1 | Connecting SMD resistors on a test substrate | 33 |
| 6.2.2 | Connecting SMD resistors in a test fixture | 35 |
| 7 Infor | mation to be given in the relevant component specification | 36 |
| Annex A (| (normative) Letter symbols and abbreviated terms | 37 |
| A.1 | Letter symbols | 37 |
| A.2 | Abbreviated terms | 38 |
| Annex B (mount res | (informative) Test results of soldering pad with Kelvin connection for surface sistors | 39 |
| B.1 | General | 39 |
| B.2 | Test procedures | 39 |
| B.2.1 | Test substrates | 39 |
| B.2.2 | 2 Test method | 41 |
| B.3 | Measurement result and studies | 42 |
| Bibliograp | bhy | 45 |
| | | |
| Figure 1 - | - Resistance measurement using two-wire sensing | 8 |
| Figure 2 - | - Variation of resistance with temperature (random example) | 10 |
| Figure 3 - | - Resistances on a resistor with lead wires | 11 |
| Figure 4 - | - SMD chip resistor on a PCB | 12 |
| Figure 5 - | - Thermoelectric e.m.f | 13 |
| Figure 6 - | - Thermocouples on a resistor with lead wires | .14 |
| Figure 7 - | - Resistance measurement affected by thermoelectric e m f | 15 |
| | | |

| Figure 8 – Four-wire resistance measurement | 17 |
|---|----------|
| Figure 9 – Offset compensation method for resistance measurement | 19 |
| Figure 10 – Current and voltage in the offset compensation method | 20 |
| Figure 11 – Current inversion method for resistance measurement | 22 |
| Figure 12 – Current and voltage in the current inversion method | 23 |
| Figure 13 – Current and voltage in the differential current inversion method | 26 |
| Figure 14 – Example of resistor specimen | 31 |
| Figure 15 – Connecting leaded resistors in a test fixture | 32 |
| Figure 16 – Resistance of cylindrical copper lead wires | |
| Figure 17 – Soldering pad of test substrate for Kelvin (four-point) connections | 34 |
| Figure 18 – Resistance of PCB conductor tracks with 35 µm copper thickness | 35 |
| Figure 19 – Example for connecting SMD resistors on a test fixture | |
| Figure B.1 – Lengths of soldering pad | 40 |
| Figure B.2 – Position of voltage sense conductor | 40 |
| Figure B.3 – Thickness of the solder printing screen and position of sense line | 43 |
| Figure B.4 – Position of voltage-sensing line | 43 |
| Figure B.5 – Soldering pad length | |
| Figure B.6 – Recommended soldering pad | 44 |
| | |
| Table 1 – Relative Seebeck coefficients of selected metals | 13 |
| Table A.1 – Letter symbols | 37 |
| | |
| Table B.1 – Thickness of solder printing screen | 41 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen | 41 42 |
| Table B.1 – Thickness of solder printing screen | 41 |
| Table B.1 – Thickness of solder printing screen | 41 42 |
| Table B.1 – Thickness of solder printing screen | |
| Table B.1 – Thickness of solder printing screen | 41 42 |
| Table B.1 – Thickness of solder printing screen | 41 42 |
| Table B.1 – Thickness of solder printing screen Table B.2 – Table of test conditions | 41 42 |
| Table B.2 – Table of test conditions | 41 42 |
| Table B.1 – Thickness of solder printing screen | 41 42 |

INTERNATIONAL ELECTROTECHNICAL COMMISSION

LOW RESISTANCE MEASUREMENTS – METHODS AND GUIDANCE

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International Standard IEC 62812 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

The text of this International Standard is based on the following documents:

| FDIS | Report on voting |
|--------------|------------------|
| 40/2665/FDIS | 40/2671/RVD |

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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